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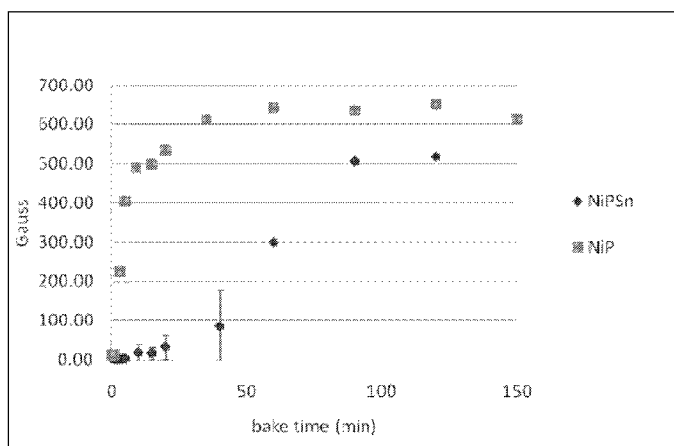
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(54) Title: ELECTROLESS NICKEL ALLOY PLATING BATH AND PROCESS FOR DEPOSITING THEREOF

**FIG. 2**

(57) Abstract: An aqueous nickel phosphorus tin alloy electroless plating bath and process for depositing a nickel phosphorus tin alloy onto a substrate, particularly an aluminum substrate for memory disk applications, wherein the nickel phosphorus tin alloy deposit provides enhanced thermal stability, as defined by the inhibition of crystallization and suppression of magnetization upon high temperature annealing when compared to typical NiP deposits.



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